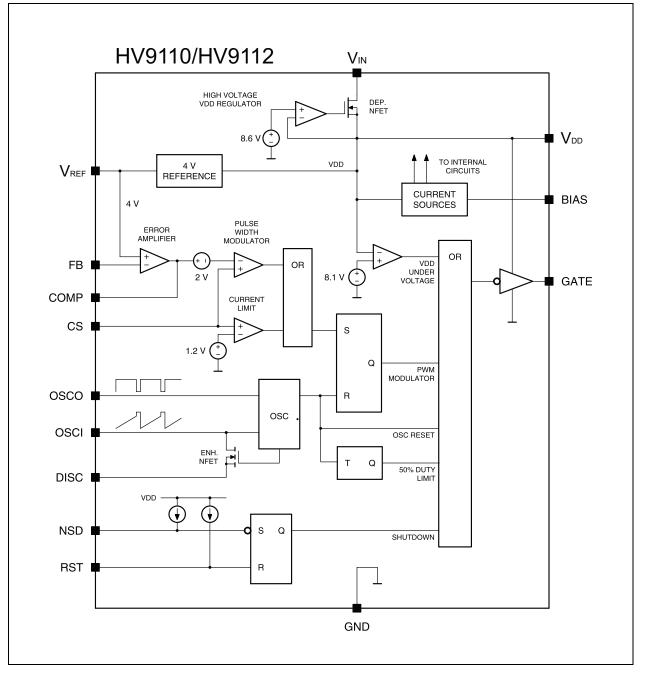
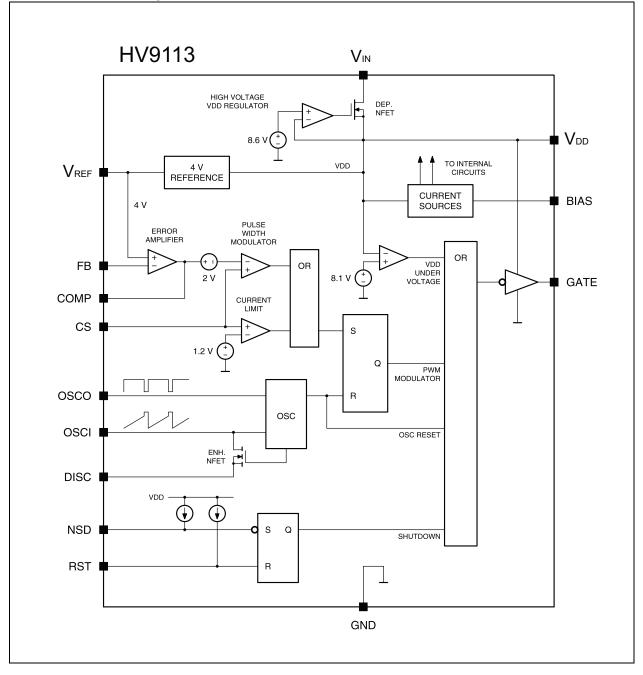
#### **Functional Block Diagram**



DS20005505A-page 2

Downloaded from Arrow.com.

#### **Functional Block Diagram**



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## 1.0 ELECTRICAL CHARACTERISTICS

### ABSOLUTE MAXIMUM RATINGS<sup>†</sup>

Input Voltage, V <sub>IN</sub>	(00)/
HV9110/HV9113	
HV9112	
Device Supply Voltage, V <sub>DD</sub>	
Logic Input Voltage Range	
Linear Input Voltage Range	
Storage Temperature Range	
Operating Temperature Range	
Power Dissipation: 14-lead SOIC	

**† Notice:** Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

## **ELECTRICAL CHARACTERISTICS**

Parame	eters	Sym.	Min.	Тур.	Max.	Units	Conditions
REFERENCE		-		-	1		
Output Voltage	HV9110/13	V <sub>REF</sub>	3.92	4	4.08	V	R <sub>I</sub> = 10 MΩ
	HV9112		3.88	4	4.12		-
	HV9110/13		3.82	4	4.16		R <sub>L</sub> = 10 MΩ, T <sub>A</sub> = –55°C to +125°C
Output Impedance		Z <sub>OUT</sub>	15	30	45	kΩ	(Note 1)
Short Circuit Current		I <sub>SHORT</sub>	_	125	250	μA	V <sub>REF</sub> = GND
Change in V <sub>REF</sub> with T	$\Delta V_{REF}$	—	0.25	—	mV/°C	T <sub>A</sub> = -55°C to +125°C ( <b>Note 1</b> )	
OSCILLATOR					•		•
Oscillator Frequency	f <sub>MAX</sub>	1	3	_	MHz	$R_{OSC} = 0\Omega$	
Initial Accuracy		f <sub>OSC</sub>	80	100	120	kHz	$R_{OSC}$ = 330 k $\Omega$ (Note )
			160	200	240		$R_{OSC}$ = 150 k $\Omega$ (Note )
V <sub>DD</sub> Regulation		—	—	_	15	%	9.5V < V <sub>DD</sub> < 13.5V
Temperature Coeffici	ent	_	_	170	_	ppm/°C	T <sub>A</sub> = -55°C to +125°C ( <b>Note 1</b> )
PWM					•		
Maximum Duty	HV9110/HV9112	D <sub>MAX</sub>	49	49.4	49.6	%	(Note 1)
Cycle	HV9113		95	97	99		
Dead Time	HV9113	D <sub>MIN</sub>	_	225	—	ns	HV9113 only (Note 1)
Minimum Duty Cycle			_	—	0	%	
Pulse Width where Pulse drops out			_	80	125	ns	(Note 1)
CURRENT LIMIT							
Maximum Input Signa	al	$V_{LIM}$	1	1.2	1.4	V	V <sub>FB</sub> = 0V
Delay to Output		t <sub>D</sub>	—	80	120	ns	V <sub>CS</sub> = 1.5V, V <sub>COMP</sub> ≤ 2V (Note 1)

ELECTRICAL CHARACTERISTICS	(CONTINUED)
----------------------------	-------------

			= 0V, R <sub>BIAS</sub> :		R <sub>OSC</sub> = 331	υ κΩ, Τ <sub>Α</sub> = :	25°C unless otherwise noted.	
Parame	eters	Sym.	Min.	Тур.	Max.	Units	Conditions	
ERROR AMPLIFIER								
Feedback Voltage	HV9110/13	V <sub>FB</sub>	3.96	4	4.04	V	V <sub>FB</sub> shorted to COMP	
	HV9112		3.92	4	4.08			
Input Bias Current		I <sub>IN</sub>	—	25	500	nA	V <sub>FB</sub> = 4V	
Input Offset Voltage		V <sub>OS</sub>	Nulle	d during	trim	—		
Open-loop Voltage G	ain	A <sub>VOL</sub>	60	80	—	dB	(Note 1)	
Unity Gain Bandwidth	ı	GB	1	1.3	—	MHz	(Note 1)	
Output Source Curren	nt	ISOURCE	-1.4	-2	—	mA	V <sub>FB</sub> = 3.4V	
Output Sink Current		I <sub>SINK</sub>	0.12	0.15	—	mA	V <sub>FB</sub> = 4.5V	
HIGH-VOLTAGE RE	GULATOR AND	START-UP						
Input Voltage	HV9110/13	V <sub>IN</sub>	—	_	120	V	I <sub>IN</sub> < 10 μA; V <sub>CC</sub> > 9.4V	
	HV9112		—	_	80			
Input Leakage Currer	nt	I <sub>IN</sub>	—	_	10	μA	V <sub>DD</sub> > 9.4V	
Regulator Turn-off Th	V <sub>TH</sub>	8	8.7	9.4	V	I <sub>IN</sub> = 10 μA		
Undervoltage Lockou	V <sub>LOCK</sub>	7	8.1	8.9	V			
SUPPLY					•			
Supply Current		I <sub>DD</sub>	_	0.75	1	mA	C <sub>L</sub> < 75 pF	
Quiescent Supply Cu	rrent	Ι <sub>Q</sub>	—	0.55	—	mA	V <sub>NSD</sub> = 0V	
Nominal Bias Current	I <sub>BIAS</sub>	—	20	_	μA			
Operating Range	V <sub>DD</sub>	9	_	13.5	V			
SHUTDOWN LOGIC					•	•		
Shutdown Delay		t <sub>SD</sub>	—	50	100	ns	C <sub>L</sub> = 500 pF, V <sub>CS</sub> = 0V (Note 1)	
NSD Pulse Width		t <sub>SW</sub>	50	_	_	ns	(Note 1)	
RST Pulse Width		t <sub>RW</sub>	50	_	_	ns	(Note 1)	
Latching Pulse Width		t <sub>LW</sub>	25	_	_	ns	V <sub>NSD</sub> , V <sub>RST</sub> = 0V(Note 1)	
Input Low Voltage		V <sub>IL</sub>	—	_	2	V		
Input High Voltage		V <sub>IH</sub>	7	_	_	V		
Input Current, Input H	ligh Voltage	IIH	—	1	5	μA	V <sub>IN</sub> = V <sub>DD</sub>	
Input Current, Input L	ow Voltage	Ι <sub>ΙL</sub>	—	-25	-35	μA	V <sub>IN</sub> = 0V	
OUTPUT					•	•		
Output High Voltage	HV9110/13		V <sub>DD</sub> -0.25	_	—	V	I <sub>OUT</sub> = 10 mA	
	HV9112	V <sub>OH</sub>	V <sub>DD</sub> -0.3	_	_			
	HV9110/13		V <sub>DD</sub> -0.3		_		I <sub>OUT</sub> = 10 mA, T <sub>A</sub> = –55°C to 125°C	
Output Low Voltage	All	V <sub>OL</sub>	_	_	0.2	V	I <sub>OUT</sub> = -10 mA	
	HV9110/13		—	—	0.3		$I_{OUT} = -10 \text{ mA},$ $T_A = -55^{\circ}\text{C to } 125^{\circ}\text{C}$	
Output Resistance	Pull up	R <sub>OUT</sub>		15	25	Ω	I <sub>OUT</sub> = ±10 mA	
Pull down Pull up				8	20	1		
		-		20	30	Ω	I <sub>OUT</sub> = ±10 mA,	
	Pull down	-		10	30	1	$T_A = -55^{\circ}C$ to 125°C	
Rise Time		t <sub>R</sub>		30	75	ns	C <sub>1</sub> = 500 pF ( <b>Note 1</b> )	
Fall Time		t <sub>F</sub>		20	75	ns	$C_{\rm L} = 500 \text{ pF} (\text{Note 1})$ $C_{\rm L} = 500 \text{ pF} (\text{Note 1})$	

Note1:Design guidance only; Not 100% tested in production.2:Stray capacitance on OSC input pin must be ≤5 pF.

### **TEMPERATURE SPECIFICATIONS**

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions			
TEMPERATURE RANGES									
Operating Temperature	—	-55		125	°C				
Storage Temperature	—	-65	—	150	°C				
PACKAGE THERMAL RESISTANCE									
14-lead SOIC	θ <sub>ja</sub>	—	83	_	°C/W				

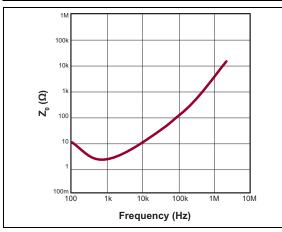
#### 1.1 Truth Table

#### **TRUTH TABLE**

SHUTDOWN	RESET	OUTPUT
Н	Н	Normal operation
Н	$H \rightarrow L$	Normal operation, no change
L	Н	Off, not latched
L	L	Off, latched
$L \rightarrow H$	L	Off, latched, no change

#### 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore outside the warranted range.



**FIGURE 2-1:** Error Amplifier Output Impedance  $(Z_0)$ .

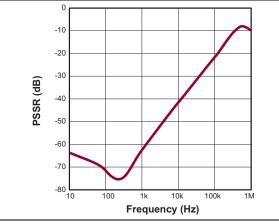
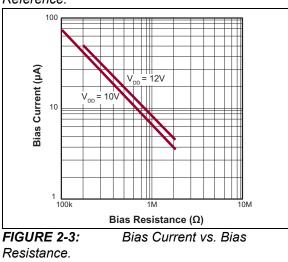


FIGURE 2-2: Reference.

PSRR – Error Amplifier and



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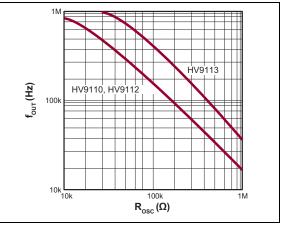


FIGURE 2-4: Output Switching Frequency vs. Oscillator Resistance.

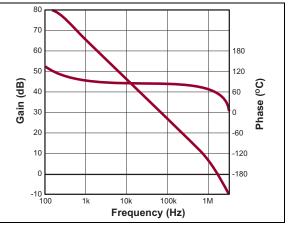


FIGURE 2-5: Error Amplifier Open-loop Gain/Phase.

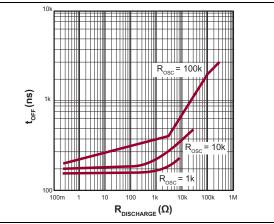


FIGURE 2-6: (HV9113 only).

R<sub>DISCHARGE</sub> vs. t<sub>OFF</sub>

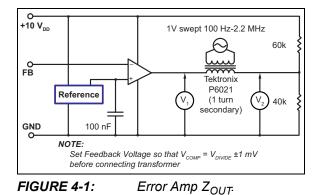
#### 3.0 **PIN DESCRIPTION**

Table 3-1 shows the pin description for HV9110/HV9112/HV9113. The locations of the pins are listed in Features.

TADLE 3-1.	FIN DESCRIFTION	
Pin Number	HV9110/HV9112/HV9113 Pin Name	Description
1	BIAS	Internal bias, current set
2	V <sub>IN</sub>	High-voltage V <sub>DD</sub> regulator input
3	CS	Current sense input
4	GATE	Gate drive output
5	GND	Ground
6	V <sub>DD</sub>	High-voltage V <sub>DD</sub> regulator output
7	OSCO	Oscillator output
8	OSCI	Oscillator input
9	DISC	Oscillator discharge, current set
10	V <sub>REF</sub>	4V reference output Reference voltage level can be overridden by an externally applied voltage source.
11	NSD	Active low input to set shutdown latch
12	RST	Active high input to reset shutdown latch
13	COMP	Error amplifier output
14	FB	Feedback voltage input

### 4.0 TEST CIRCUITS

The test circuits for characterizing error amplifier output impedance, Z<sub>OUT</sub>, and error amplifier, power supply rejection ratio, PSRR, are shown in Figure 4-1 and Figure 4-2.



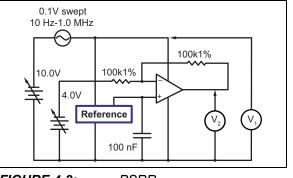


FIGURE 4-2: PSRR.

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## 5.0 DETAILED DESCRIPTION

#### 5.1 High-Voltage Regulator

The high-voltage regulator included in HV9110/HV9112/HV9113 consists of a high-voltage Nchannel Depletion-mode DMOS transistor driven by an error amplifier, providing a current path between the V<sub>IN</sub> terminal and the V<sub>DD</sub> terminal. The maximum current, about 20 mA, occurs when  $V_{DD}$  = 0, with current reducing as  $V_{\text{DD}}$  rises. This path shuts off when  $V_{\text{DD}}$ rises to somewhere between 8V and 9.4V. So, if  $V_{DD}$  is held at 10V or 12V by an external source, no current other than leakage is drawn through the high voltage transistor. This minimizes dissipation within the highvoltage regulator.

Use an external capacitor between  $V_{DD}$  and GND. This capacitor should have good high-frequency characteristics. Ceramic caps work well.

The device uses a compound resistor divider to monitor  $V_{DD}$  for both the undervoltage lockout circuit and the shutoff circuit of the high-voltage FET. Setting the undervoltage sense point about 0.6V lower on the string than the FET shutoff point guarantees that the undervoltage lockout releases before the FET shuts off.

#### 5.2 Bias Circuit

HV9110/HV9112/HV9113 require an external bias resistor, connected between the Bias pin and GND to set currents in a series of current mirrors used by the analog sections of the chip. The nominal external bias current requirement is 15 μA to 20 μA, which can be set by a 390 kΩ to 510 kΩ resistor if V<sub>DD</sub> = 10V, or a 510 kΩ to 680 kΩ resistor if V<sub>DD</sub> = 12V. A precision resistor is not required, ±5% meets device requirements.

#### 5.3 Clock Oscillator

The clock oscillator of the HV9110/HV9112/HV9113 consists of a ring of CMOS inverters, timing capacitors, and a capacitor-discharge FET. A single external resistor between the OSCI and OSCO sets the oscillator frequency. (See Figure 2-4.)

The HV9110 and HV9112 include a frequency-dividing flip-flop that allows the part to operate with a 50% duty limit. Accordingly, the effective switching frequency of the power converter is half the oscillator frequency. (See Figure 2-4.)

An internal discharge FET resets the oscillator ramp at the end of the oscillator cycle. The discharge FET is externally connected to GND, by way of a resistor. The resistor programs the oscillator dead time at the end of the oscillator period. The oscillator turns off during shutdown to reduce supply current by about 150  $\mu\text{A}.$ 

#### 5.4 Reference

The reference of the HV9110/HV9112/HV9113 consists of a band-gap reference, followed by a buffer amplifier, which scales the voltage up to 4V. The scaling resistors of the buffer amplifier are trimmed during manufacture so that the output of the error amplifier, when connected in a gain of –1 configuration, is as close to 4V as possible. This nulls out the input offset of the error amplifier. As a consequence, even though the observed reference voltage of a specific part may not be exactly 4V, the feedback voltage required for proper regulation will be 4V.

An approximately 50 k $\Omega$  resistor is located internally between the output of the reference buffer amplifier and the circuitry it feeds—reference output pin and non-inverting input to the error amplifier. This allows overriding the internal reference with a low impedance voltage source  $\leq$  6V. Using an external reference reinstates the input offset voltage of the error amplifier. Overriding the reference should seldom be necessary.

The reference of the HV9110/HV9112/HV9113 is a high-impedance node, and usually there will be significant electrical noise nearby. Therefore, a bypass capacitor between the reference pin and GND is strongly recommended. The reference buffer amplifier is compensated to be stable with a capacitive load of 0.01  $\mu$ F to 0.1  $\mu$ F.

#### 5.5 Error Amplifier

The error amplifier on HV9110/HV9112/HV9113 is a low-power, differential-input, operational amplifier. A PMOS input stage is used, so the common mode range includes ground and the input impedance is high.

#### 5.6 Current Sense Comparators

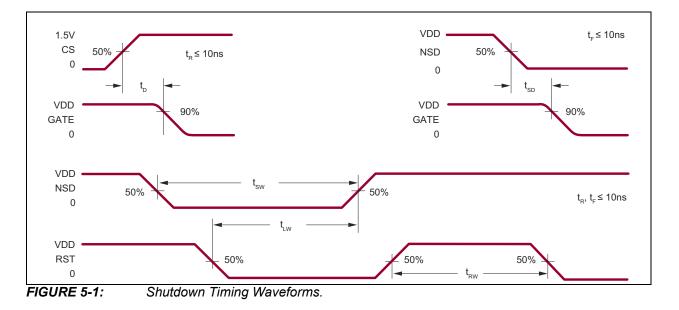
The HV9110/HV9112/HV9113 use a dual-comparator system with independent comparators for modulation and current limiting. This provides the designer greater latitude in compensation design, as there are no clamps, except ESD protection, on the compensation pin.

#### 5.7 Remote Shutdown

The NSD and RST pins control the shutdown latch. These pins have internal current-source pull-ups so they can be driven from open drain logic. When not used they should be left open or connected to  $V_{DD}$ .

#### 5.8 Output Buffer

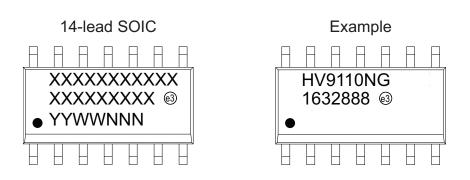
The output buffer of HV9110/HV9112/HV9113 is of standard CMOS construction P-channel pull-up and N-channel pull-down. Thus, the body-drain diodes of the output stage can be used for spike clipping. External Schottky diode clamping of the output is not required.



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### 6.0 PACKAGING INFORMATION

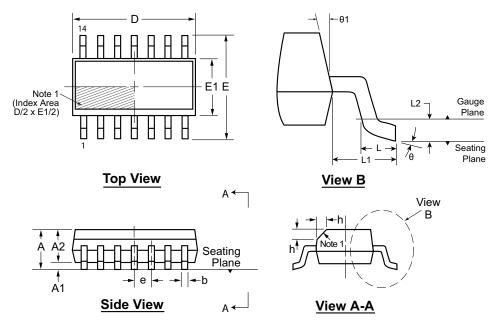
#### 6.1 Package Marking Information



Legend	: XXX Y YY WW NNN @3 *	Product Code or Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC <sup>®</sup> designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note:	be carried characters	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available s for product code or customer-specific information. Package may or e the corporate logo.

# 14-Lead SOIC (Narrow Body) Package Outline (NG)

8.65x3.90mm body, 1.75mm height (max), 1.27mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Note:

1. This chamfer feature is optional. If it is not present, then a Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbo	ol	Α	A1	A2	b	D	Е	E1	е	h	L	L1	L2	θ	θ1
	MIN	1.35*	0.10	1.25	0.31	8.55*	5.80*	3.80*		0.25	0.40			<b>0</b> 0	5°
Dimension (mm)	NOM	-	-	-	-	8.65	6.00	3.90	1.27 BSC	-	-	1.04 REF	0.25 BSC	-	-
()	MAX	1.75	0.25	1.65*	0.51	8.75*	6.20*	4.00*	200	0.50	1.27		200	<b>8</b> 0	15 <sup>0</sup>

JEDEC Registration MS-012, Variation AB, Issue E, Sept. 2005. \* This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

NOTES:

#### APPENDIX A: REVISION HISTORY

#### Revision A (June 2016)

- Merged Supertex Doc #s DSFP-HV9110, DSFP-HV9112 and DSFP-DSFP-HV9113 to Microchip DS20005505A.
- Revised Electrical Characteristics to accommodate the merged products.
- Updated pin names to reflect new naming convention.
- Significant text changes to **Detailed Description**.
- Minor text changes throughout.

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### PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

	XX - X - X       Package Environmental Media Options Type	Controller 10 age Range,	Current-mode PWM V to 120V Input Volt- , 49% Duty Cycle, C Package, 53/Tube
Device:	HV9110 =High-voltage Current-mode PWM Controller, 10V to 120V Input Voltage Range, 49% Duty CycleHV9112 =High-voltage Current-mode PWM Controller, 9V to 80V Input Voltage Range, 49% Duty CycleHV9113 =High-voltage Current-mode PWM Controller, 10V to 120V Input Voltage Range, 99% Duty Cycle	Voltage R Cycle,14-lea 53/Tube c) HV9113NG-G: High-voltage Controller, 10 age Range, 9	e Current-mode oller, 9V to 80V Input ange, 49% Duty ad SOIC Package, Current-mode PWM W to 120V Input Volt- 19% Duty Cycle, c Package, 53/Tube
Package:	NG = 14-lead SOIC		
Environmental	G = Lead (Pb)-free/RoHS-compliant Package		
Media Type:	(blank) = 53/Tube for an NG package		

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